Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .004” X .004”**

**Backside Potential: Vcc (or floating)**

**Mask Ref: HCT174T**

**APPROVED BY: DK DIE SIZE .056” X .070” DATE: 8/26/21**

**MFG: TEXAS INSTRUMENTS THICKNESS .011” P/N: 54HCT174**

**DG 10.1.2**

#### Rev B, 7/19/02